FORM PTO-1449

INFORMATION DISCLOSURE CITATION

Attorney Docket: 4024-4021	Serial No.: 09/897,158
Applicant: Dudoff et al.	
Filing Date: June 29, 2001	Group Art Unit: 2814

U.S. PATENT DOCUMENTS

Examiner Initial	Patent Number	Publication Date	Name	Class	Sub-Class	Filing Date
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	5,266,794		Olbright et al.			November 30, 1993
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Examiner	Douglas Wilson	Date Considered	6 Nov 02

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FOREIGN PATENT DOCUMENTS						
Examiner Initial	Patent Number	Publication Date	Country	Class	Sub-Class	Translation
						☐ Yes ☐ No
						☐ Yes ☐ No
						☐ Yes ☐ No

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Examiner	Douglas Wille	Date Considered	6 Nov 02

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